

Anderson 6-17-18-166-3

IN THE TITLE:

Please change the *Title* as follows:

--- Method and System for Eliminating Extrusions in Semiconductor Vias--

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IN THE SPECIFICATION:

Please insert the following text as the first sentence in the specification:

--This is a divisional of US Patent Application No. 09/586,586, filed June 2, 2000
and now US Patent 6,720,261.--